

ENGIS[®] MICROTECH AM-15 LAPPING & POLISHING MACHINE



The **Engis Corporation** AM-15 bench-top or modular cart-top machine is designed to accommodate a variety of surface preparation requirements. Specifically, it is capable of backthinning, lapping and/or polishing of:

- Semiconductor (silicon, germanium, etc.) materials
- Compound Semiconductor (GaAs, GaN & InP) materials
- Electro-Optics (LiNbO₃, BBO, etc)
- Ceramic, Silicon Carbide, Sapphire & Glass

This system is excellent for R&D work at Universities, Research Centers and for prototype and small volume work in the commercial sector, especially when development is needed without conflicting with production capability. It is a fully functional, rigid, yet compact, bench-top machine with advanced features & standard 15" diameter platen.

ADVANCED MATERIALS PRODUCTS

FOR ADDITIONAL INFORMATION CONTACT THE ENGIS MICROTECH TEAM AT

WWW.ENGISCA.COM



AM-15 SPECIFICATIONS

- **Graphic Logic Controller**, for operator friendly programming and machine control
- **Rigid Cast Aluminum Base**
- **Precision Cartridge Spindle**
- **Variable Speed Main Spindle with Soft Start and Stop**
- **Fully Programmable Pressure Head**
- **“Spin-Up” Feature** to avoid damage of the final polished component
- **Totally Enclosed Working Area Fully Interlocked**

TECHNICAL DATA	
LAPPING PLATE DIAMETER	380MM (15")
NO. OF STATIONS	3
POWER HEADS	1 STD - 2 OPTIONAL
INSIDE DIAMETER OF CONDITIONING RING	140MM (5.5")
WORK TABLE DIMENSIONS	711MM X 762MM (28" X 30")
PLATE RPM RANGE	3-120 RPM
POWER HEAD SPINDLE SPEED	3 - 100 RPM (REVERSABLE)
POWER HEAD DOWN PRESSURE	4.5 - 45 KGMS (10 - 100 LBS)
POWER STATION PRESSURE AND SPEED RAMP-UP	ADJUSTABLE & PROGRAMMABLE
MAIN DRIVE MOTOR (H.P. RATING)	0.5 H.P. AIR COOLED
OPERATING VOLTAGE	115 VAC, 1-PHASE, 50/60 HZ
FLC @ 115VAC (60Hz)	8.6A
GRAPHIC LOGIC CONTROLLER (PROGRAMMABLE)	STANDARD
DIMENSIONS	785MM X 775MM X 915MM (31" X 30.5" X 36")
ESTIMATED SHIPPING WEIGHT	250 Kg (550 LBS)

*ENGIS IS ABLE TO DELIVER A COMPLETE SYSTEM TO FIT EACH CUSTOMER'S UNIQUE REQUIREMENTS
AND OPTIMIZE THE MOST DEMANDING APPLICATIONS*

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| <ul style="list-style-type: none"> ◦ HYPREZ COMPOSITE LAP PLATES ◦ DIAMOND AND COLLOIDAL LAPPING & POLISHING SLURRIES ◦ LUBRICANTS & CLEANERS | <ul style="list-style-type: none"> ◦ POLISHING PADS/CLOTHS ◦ WAFER MOUNTING EQUIPMENT ◦ CONDITIONING RINGS |
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3465 Mainway, Unit #2
Burlington, Ontario L7M 1A9
Telephone: 905-632-3016
engiscanada@engis.com

www.engisca.com